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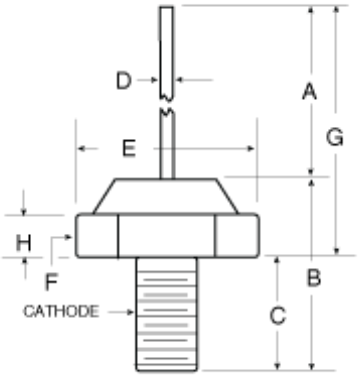
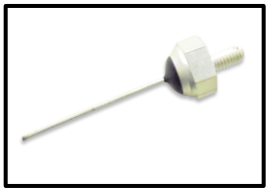
1N1622
Silicon Power Rectifier





Dim.	Inches		Milimeter		
	Minimum	Maximum	Minimum	Maximum	Notes
A	---	---	---	---	1
B	.424	.437	10.77	11.10	
C	---	.505	---	12.82	
D	.600	.800	15.24	20.32	
E	.422	.453	10.72	11.50	
F	.075	.175	1.91	4.44	
G	---	.405	---	10.29	
H	.163	.189	4.15	4.80	2
J	---	.310	---	7.87	
M	---	.350	---	8.89	Dia
N	.020	.065	.510	1.65	
P	.070	.100	1.78	2.54	Dia

	A	B	C	D	E	F	G	H	THD
S43	1.50 MIN	.531 .665	.334	.051	.563	.50 AIF			10 - 32
S43a			.240 MAX	0.23		216 500	.984 MIN	.157	M3

- Glass Passivated Die
- Low Forward Voltage
- 250A Surge Rating
- Glass to metal seal construction
- V_{RRM} to 1600 V

Electrical Characteristics

Average forward current	$I_{F(AV)}$	22 Amps	T_C = 134°C, square wave, $R_{\theta JC}$ = 2.5°C/W
Maximum surge current	I_{FSM}	250 Amps	8.3ms, half sine, T_J = 200°C
Max I^2t for fusing	I 2 t	260 A^2s	
Max peak forward voltage	V_{FM}	1.2 Volts	I_{FM} = 30A; T_J = 25°C *
Max peak reverse current	I_{RM}	10 µA	V_{RRM}, T_J = 25°C
Max peak reverse current	I_{RM}	1.0 mA	V_{RRM}, T_J = 150°C
Max Recommended Operating Frequency		10kHz	

Pulse test: Pulse width 300µsec. Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temperature range	T_{STG}	-65°C to 200°C
Operating junction temp range	T_J	-65°C to 200°C
Maximum thermal resistance	$R_{\theta JC}$	2.5°C/W Junction to Case
Mounting torque		25 – 30 inch pounds
Weight		.16 ounces (5 grams) typical

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Figure 1
Maximum Forward Characteristics

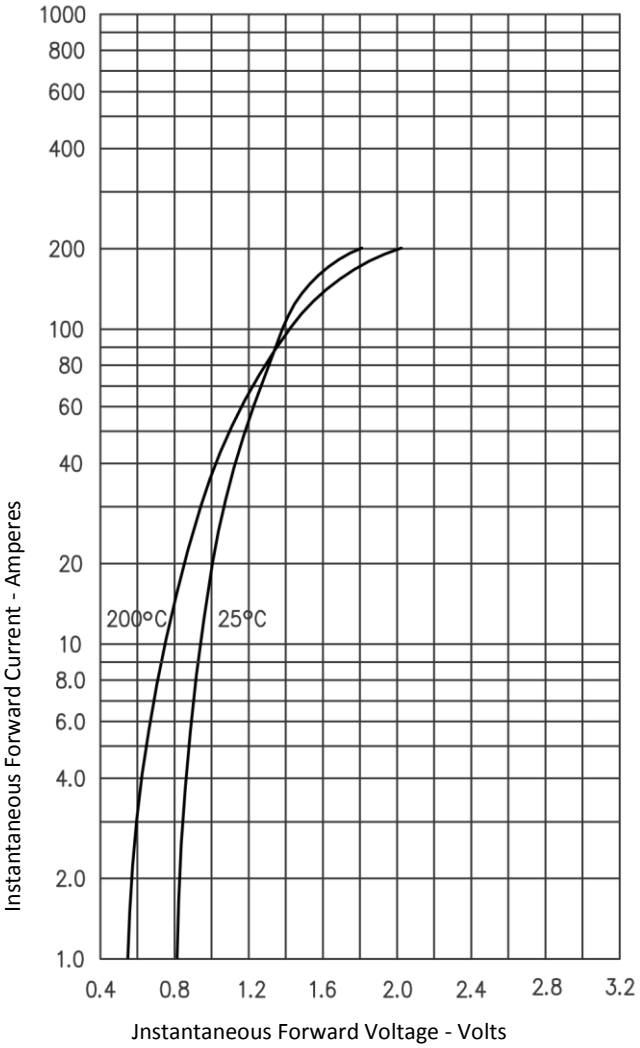


Figure 2
Typical Reverse Characteristics

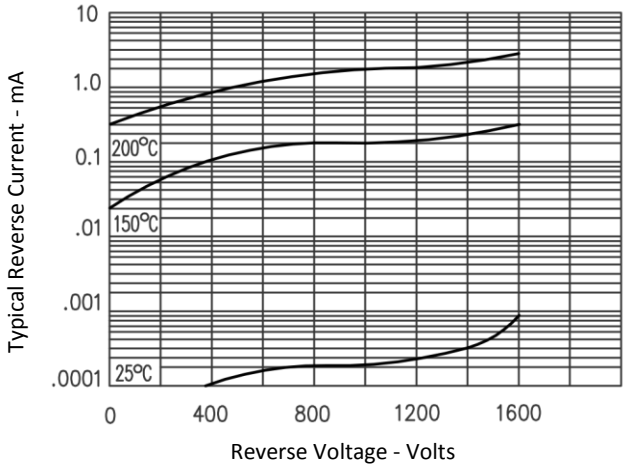


Figure 3
Forward Current Derating

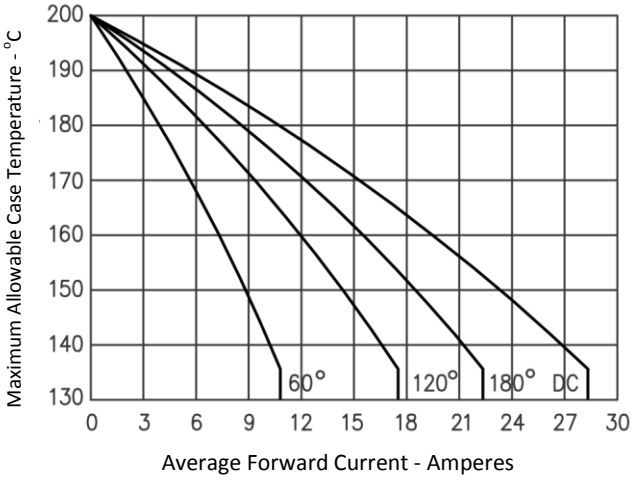


Figure 4
Maximum Forward Power Dissipation

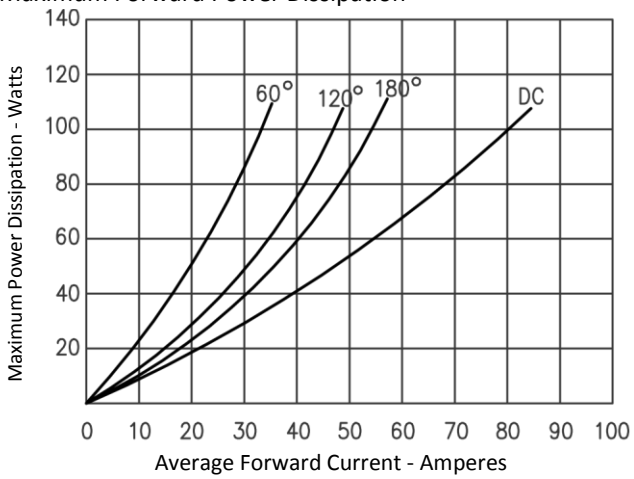
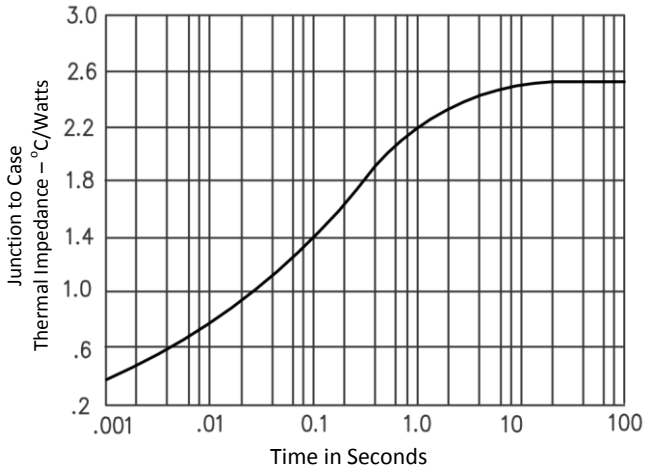


Figure 5
Transient Thermal Impedance



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